

Title (en)  
INSTALLATION FOR POURING LIQUID METAL, AND PROCESS FOR ITS IMPLEMENTATION

Publication  
**EP 0305426 B1 19910313 (FR)**

Application  
**EP 88901871 A 19880219**

Priority  
FR 8702225 A 19870220

Abstract (en)  
[origin: WO8806068A1] Installation for pouring liquid metal, comprising a metallurgical receptacle (1), designed to contain liquid metal (2), provided with a pouring hole (6) and under said hole (6) a principal closing and opening device (8) for same (6). Also an auxiliary device (12) for preheating, sealing and unsealing said pouring hole (6), disposed thereabove (6) and comprising an elongated element (13) designed for partial immersion in the liquid metal (2) and made of a refractory and/or insulating material (34) which sinters on contact with the liquid metal; also means (14, 15, 17, 18, 21) for holding the elongated element (13) over the pouring hole (6), so sealing it before and during the first stage of the pouring of the liquid metal (2) into the receptacle (1) and for lifting said element (13) from the pouring hole (6), said element consisting of at least one longitudinal pipe (23) issuing at right angles with, or in the vicinity of the pouring hole (6) and connected with at least one pressurized gas source (30), enabling the preheating and/or unsealing of the hole (6). Application particularly in preheating and/or unsealing of the pouring hole (6) of a metallurgical receptacle (1).

IPC 1-7  
**B22D 41/14; F27D 3/15**

IPC 8 full level  
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